



0.2A SCHOTTKY BARRIER DIODE IN CHIP SCALE PACKAGE

Product Summary

V _{RRM} (V)	I _O (mA)	V _F Max (V) @ +25°C	I _R Max (μA) @ +25°C
30	200	0.44	120

Description

The SDM02L30CP3 is a 30-volt 200mA Schottky Barrier Diode that is optimized for very low forward voltage drop and low leakage current. It's housed in a compact Chip Scale Package (CSP) that occupies only 0.18mm² board space. The low thermal resistance enables designers to meet design challenges of increasing efficiency while reducing board space. It is ideally suited for use in portable applications.

Applications

- Blocking Diode
- Reverse Protection Diode
- Boost Diode

Features and Benefits

- 0.18mm² Footprint, Off Board Profile of 0.275mm
- Very Low Forward Voltage Minimizes Power Dissipation Losses
- Low Leakage Maximizes Battery Power
- Soft, Fast Switching Capability
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: X3-WLB0603-2
- Moisture Sensitivity: Level 1 per J-STD-020
- · Polarity Indicator: Cathode Dot
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 @
- Weight: 0.1mg (Approximate)

X3-WLB0603-2



Top View



Bottom View

Ordering Information (Note 4)

Part Number	Case	Packaging
SDM02L30CP3-7	X3-WLB0603-2	10,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

X3-WLB0603-2



P = Product Type Marking Code Dot Denotes Cathode Pin



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Average Rectified Output Current	lo	200	mA
Repetitive Peak Forward Current, $t_P \le 1 ms$; $\delta \le 0.25$	I _{FRM}	4	А
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	6	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Notes 5 & 6)	$R_{ hetaJA}$	250	°C/W
Operating Temperature Range (Note 6)	TJ	-55 to +150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

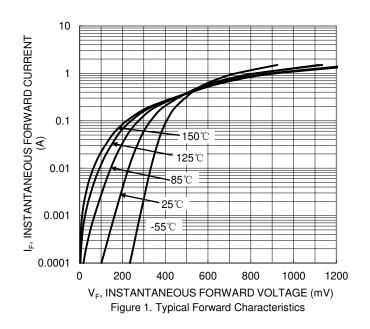
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	VF		0.16 0.23 0.33 0.39	0.20 0.29 0.38 0.44	V	I _F = 1mA, T _J = +25°C I _F = 10mA, T _J = +25°C I _F = 100mA, T _J = +25°C I _F = 200mA, T _J = +25°C
Leakage Current (Note 7)	I _R	_ _	9 35	30 120	μΑ	$V_R = 10V, T_J = +25$ °C $V_R = 30V, T_J = +25$ °C
Junction Capacitance	Ст	_	10	_	pF	V _R = 5V, T _J = +25°C, f = 1MHz

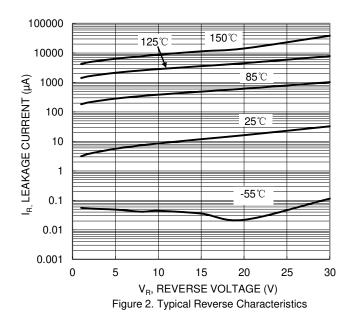
Notes:

- 5. Device mounted on FR-4 substrate PC board, with minimum recommended pad layout per http://www.diodes.com/package-outlines.html.
 6. For Schottky barrier diodes, thermal runaway must be avoided with adequate thermal dissipation in design to prevent T_J keeping rising under the operating conditions in applications.
 7. Short duration pulse test used to minimize self-heating effect.



Typical Electrical Characteristics





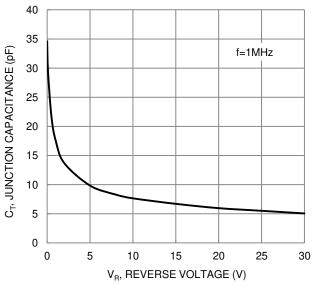


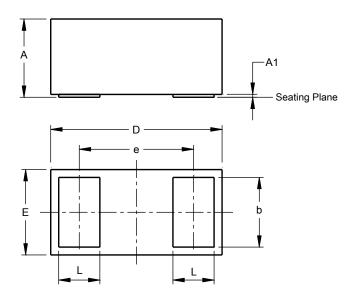
Figure 3. Typical Junction Capacitance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB0603-2

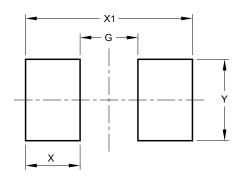


X3-WLB0603-2					
Dim	Min	Max	Тур		
Α	0.250	0.300	0.275		
A 1	0.00	0.01	-		
b	0.220	0.280	0.245		
D	0.575	0.625	0.600		
Е	0.275	0.325	0.300		
е	-	-	0.400		
L	0.120	0.180	0.144		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X3-WLB0603-2



Dimensions	Value (in mm)	
G	0.206	
X	0.194	
Υ	0.291	
X1	0.594	



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